This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:** 

1. (Currently Amended) Process chamber of an installation for the thermal treatment of

printed circuit boards (1), with a fan wheel (30) supported on a shaft (10) parallel to the

printed circuit boards (1), said fan wheel (30) being disposed between two walls (6, 7) of

the process chamber, characterized in that the fan wheel (30) is open at its two opposing

end faces (13, 14) and the two opposing end faces (13, 14) are configured as a pair of

intakes at such a distance from the walls (6, 7) of the process chamber that gas flows in

unimpeded in two substreams (16, 17) between into the two opposing end faces (13, 14)

of the fan wheel (30) and the walls (6, 7) and flows out from the cylindrical surface of the

fan wheel (30) over the length thereof and in the extent of the process chamber in the

form of a ribbon-shaped gas stream (28), said gas stream (28) being directed essentially

in said cross section through a channel (29, 24) onto the printed circuit boards (1).

2. (Currently amended) Process chamber according to claim 1, characterized in that said

process chamber is contained in a housing (2), said housing (2) forming with housing

plates (19, 20) an intermediate space (18) with respect to the-walls (6, 7) of the process

chamber, in which intermediate space (18) the two substreams (16, 17) are guided and are

supplied through penetrations (22, 23) in the housing plates (19, 20) to the two opposing

end faces of the fan wheel (30).

3. (Original) Process chamber according to claim 1, characterized in that the fan wheel (30)

is supported on one side in one of the two walls (6, 7).

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